修订记录 / Revised record

A	2018-1				
B	2019-5-11	1 4 6 7	，		
C	2022-1-4	2/3	Cj 180 600 RθJA 60 改为 45；更新曲线图 Fig.1 Forward Current Derating Curve（90 改到 125℃）IR 25℃ 0.1 改为 1，增加 100 IR SMBF-S-SSL510BF-5 A100V.pdf		

SSL510BF

Rev.C Jan.-2022

描述 / Descriptions

100V 5.0A SMBF

Surface Mount Schottky Barrier Rectifier, Reverse Voltage:100V,Forward Current:5.0A,SMBF thin package.

特 / Features

Low power loss, high efficiency, High forward surge current capability, For use in low voltage, high frequency inverters, and polarity protection applications,For surface mounted applications,Halogen free product.

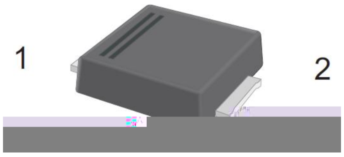
用途 / Applications

.

General purpose.

内部等效 路 / Equivalent Circuit

引 排列 / Pinning



印章代码 / Marking

See Marking Instructions.

Note:

1） Measured at 1MHz and applied reverse voltage of 4 V D.C.

2） P.C.B. mounted with 2.0 X2.0" (5 X 5 cm) copper pad areas.

参数 Parameter	参数符号 Symbol	测试条件 Test condition	数值 Rating	单位 Unit
Max Instantaneous Forward Voltage	V_F	I_F=5.0A	0.6	V
Maximum DC Reverse Current at Rated DC Reverse Voltage	I_R	T_a=25℃	1.0	mA

数曲线 / Electrical Characteristic Curve

Fig.1 Forward Current Derating Curve

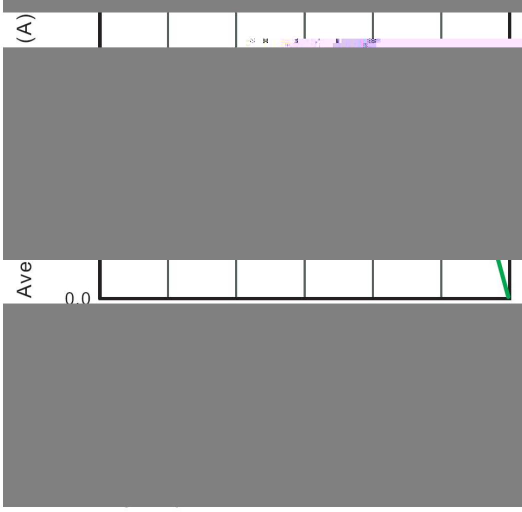
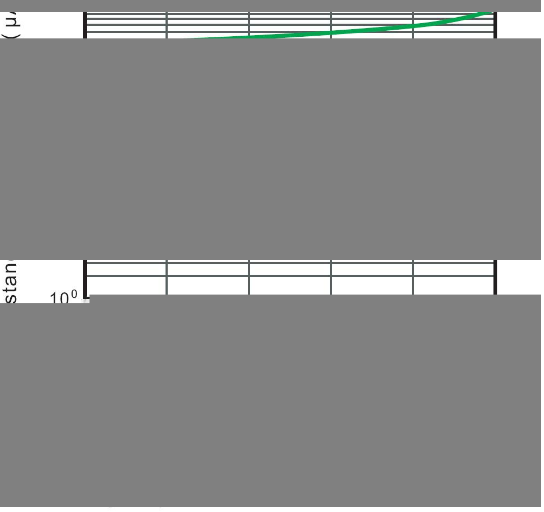
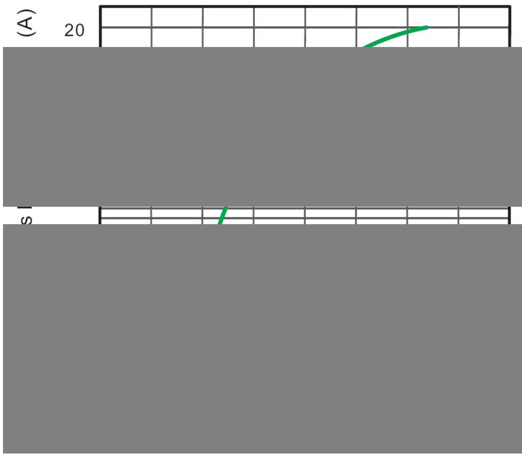


Fig.2 Typical Reverse Characteristics





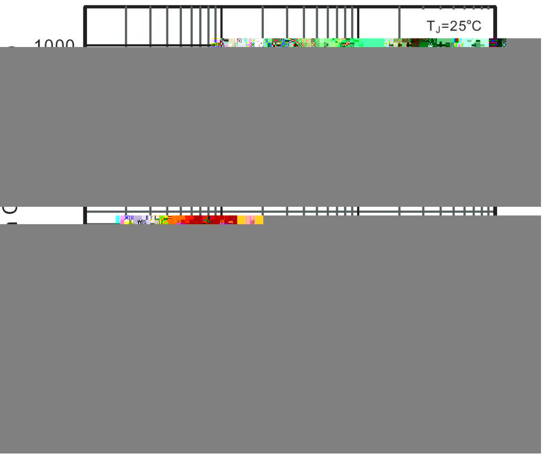


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current

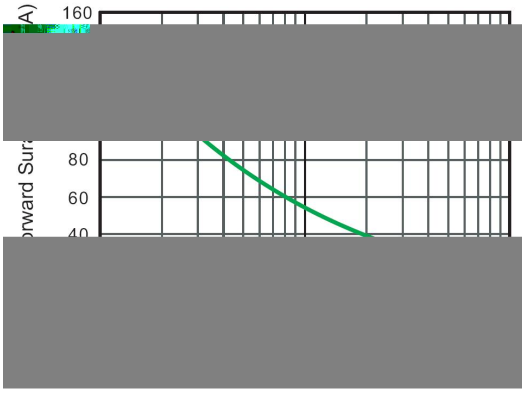
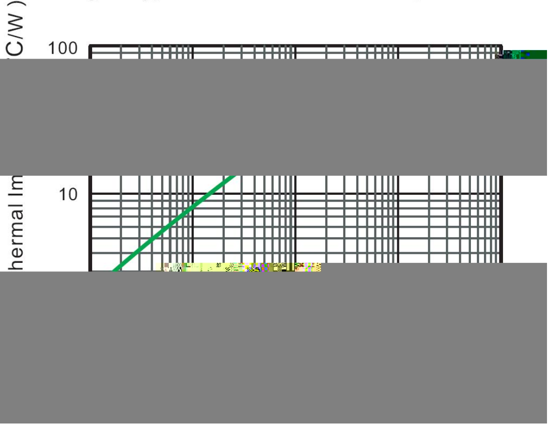


Fig.6- Typical Transient Thermal Impedance

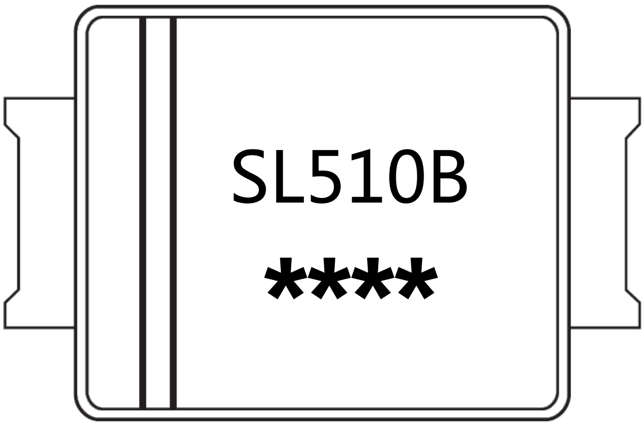


尺寸 / Package Dimensions

SMBF

印章 / Marking Instructions

印章 / Marking Instructions



说明：

SL510B： 为型号代码

**** ： 为生产批号追溯码，第 1 个*为年月代码，后面 3 个*为当月小批号代码

Note:

SL510B： Product Type Code

****： Lot No. Code，The 1st * means:YM Code，The last 3 * means:little Lot No Code

回 曲线 铅(无) / Temperature Profile for IR Reflow Soldering(Pb-Free)

	Note:
1 150 180 60 90sec;	1.Preheating:150~180℃, Time:60~90sec.
2 245±5 5±0.5sec;	2.Peak Temp.:245±5℃, Duration:5±0.5sec.
3 2 10℃/sec.	3. Cooling Speed: 2~10℃/sec.

耐 热试验 / Resistance to Soldering Heat Test Conditions

260±5℃ 10±1 sec. Temp.:260±5℃ Time:10±1 sec

包 规格 / Packaging SPEC.

/ REEL

Package Type	Units	Dimension	(unit mm^3)